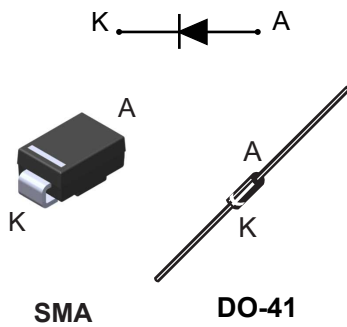


## 1000 V - 1 A high efficiency ultrafast diode



### Features

- Low forward voltage drop
- High reliability
- High surge current capability
- Soft switching for reduced EMI disturbances
- Planar technology
- ECOPACK2 compliant

### Applications

- Switching diode
- Auxiliary power supply

### Description

The STTH110, which is using ST ultrafast high voltage planar technology, is especially suited for free-wheeling, clamping, snubbing, demagnetization in power supplies and other power switching applications.

Product status	
STTH110	
Product summary	
Symbol	Value
$I_{F(AV)}$	1 A
$V_{RRM}$	1000 V
$T_{j(max.)}$	175 °C
$V_{F(typ.)}$	1.42 V

# 1 Characteristics

**Table 1. Absolute ratings (limiting values at 25 °C, unless otherwise specified)**

Symbol	Parameter		Value	Unit
$V_{RRM}$	Repetitive peak reverse voltage		1000	V
$V_{RMS}$	Voltage rms		700	V
$I_{F(AV)}$	Average forward current $\delta = 0.5$ , square wave	SMA $T_L = 125\text{ °C}$	1	A
		DO-41 $T_L = 100\text{ °C}$		
$I_{FSM}$	Surge non repetitive forward current	SMA	18	A
		DO-41 $t_p = 8.3\text{ ms sinusoidal}$	20	
$T_{stg}$	Storage temperature range		-50 to +175	°C
$T_j$	Maximum operating junction temperature		+175	°C

**Table 2. Thermal resistance parameter**

Symbol	Parameter		Max. value	Unit
$R_{th(j-l)}$	Junction to lead	SMA	30	°C/W
	Junction to lead	Lead length = 10 mm	45	
$R_{th(j-a)}$	Junction to ambient		DO-41	

For more information, please refer to the following application note :

- AN5088 : Rectifiers thermal management, handling and mounting recommendations

**Table 3. Static electrical characteristics**

Symbol	Parameter	Test conditions		Min.	Typ.	Max.	Unit
$I_R^{(1)}$	Reverse leakage current	$T_j = 25\text{ °C}$	$V_R = 1000\text{ V}$	-		10	$\mu\text{A}$
		$T_j = 125\text{ °C}$		-		50	
$V_F^{(2)}$	Forward voltage drop	$T_j = 25\text{ °C}$	$I_F = 1\text{ A}$	-		1.7	V
		$T_j = 150\text{ °C}$		-	0.98	1.42	

1. Pulse test:  $t_p = 5\text{ ms}$ ,  $\delta < 2\%$

2. Pulse test:  $t_p = 380\text{ }\mu\text{s}$ ,  $\delta < 2\%$

To evaluate the conduction losses, use the following equation:

$$P = 1.20 \times I_{F(AV)} + 0.225 \times I_{F(RMS)}^2$$

For more information, please refer to the following application notes related to the power losses :

- AN604: Calculation of conduction losses in a power rectifier
- AN4021: Calculation of reverse losses on a power diode

**Table 4. Dynamic characteristics ( $T_j = 25\text{ °C}$  unless otherwise stated)**

Symbol	Parameters	Test conditions	Min.	Typ.	Max.	Unit
$t_{rr}$	Reverse recovery time	$I_F = 0.5\text{ A}$ , $I_{rr} = 0.25\text{ A}$ , $I_R = 1\text{ A}$	-	-	75	ns
$t_{fr}$	Forward recovery time	$I_F = 1\text{ A}$ , $di_F/dt = 50\text{ A}/\mu\text{s}$ , $V_{FR} = 1.1 V_{F(max)}$	-	-	300	ns
$V_{FP}$	Forward recovery voltage		-	-	18	V

### 1.1 Characteristics (curves)

Figure 1. Conduction losses versus average current

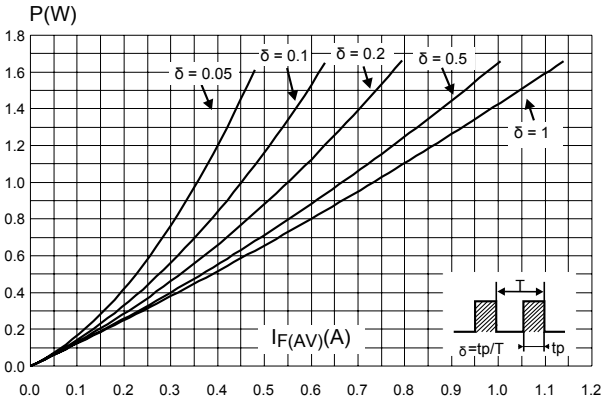


Figure 2. Forward voltage drop versus forward current (typical values)

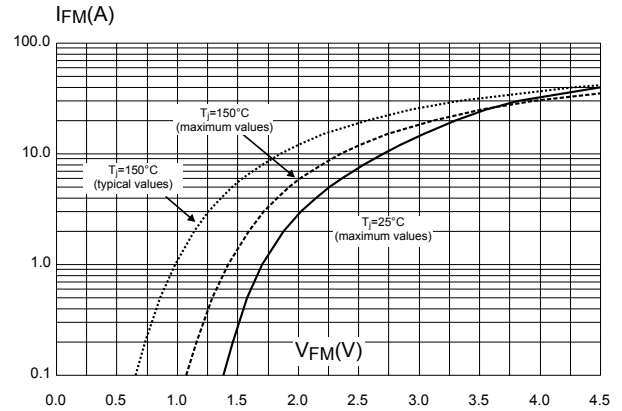


Figure 3. Relative variation of thermal impedance junction to ambient versus pulse duration (DO-41)

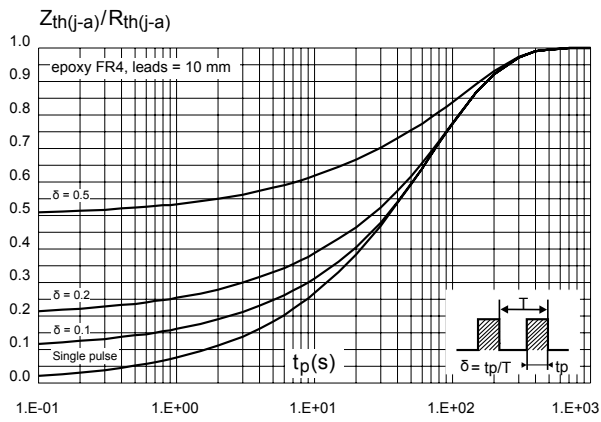
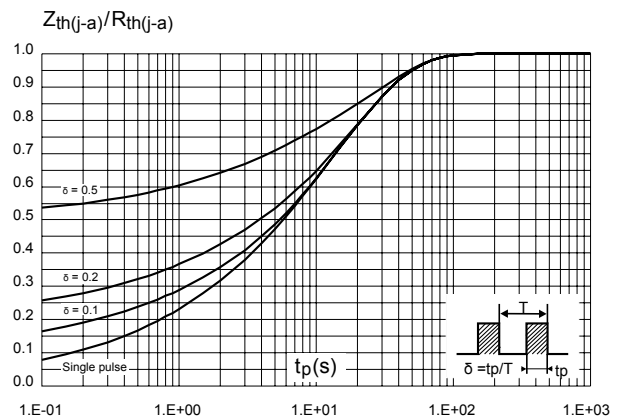
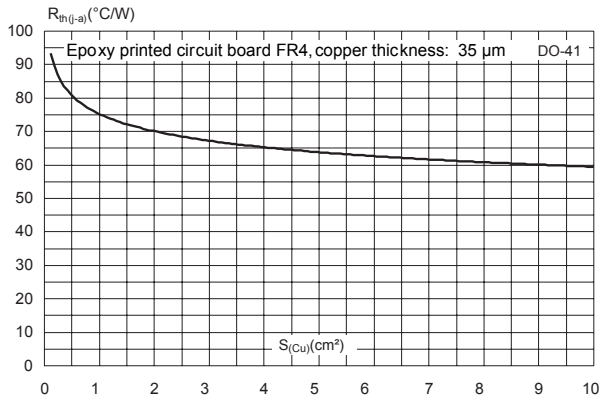


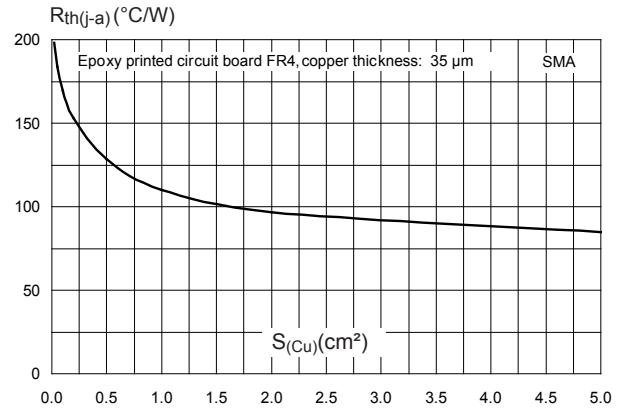
Figure 4. Relative variation of thermal impedance junction to ambient versus pulse duration(SMA)



**Figure 5. Thermal resistance junction to ambient versus copper surface under each lead (DO-41)**



**Figure 6. Thermal resistance junction to ambient versus copper surface under each lead (typical values) (SMA)**



## 2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of **ECOPACK** packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK is an ST trademark.

### 2.1 DO-41 package information

- Epoxy meets UL 94, V0
- Band indicates cathode
- Bending method (DO-41): see Application note AN1471

Figure 7. DO-41 package outline

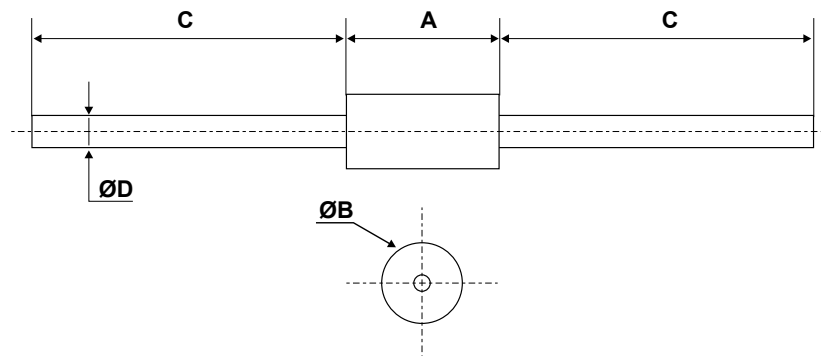


Table 5. DO-41 package mechanical data

Ref.	Dimensions					
	Millimeters			Inches (for reference only)		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	4.07	-	5.20	0.160	-	0.205
B	2.04	-	2.71	0.080	-	0.107
C	25.40	-		1.000	-	
D	0.71	-	0.86	0.028	-	0.0034

## 2.2 SMA package information

- Epoxy meets UL94, V0
- Cooling method : by conduction (C)

Figure 8. SMA package outline

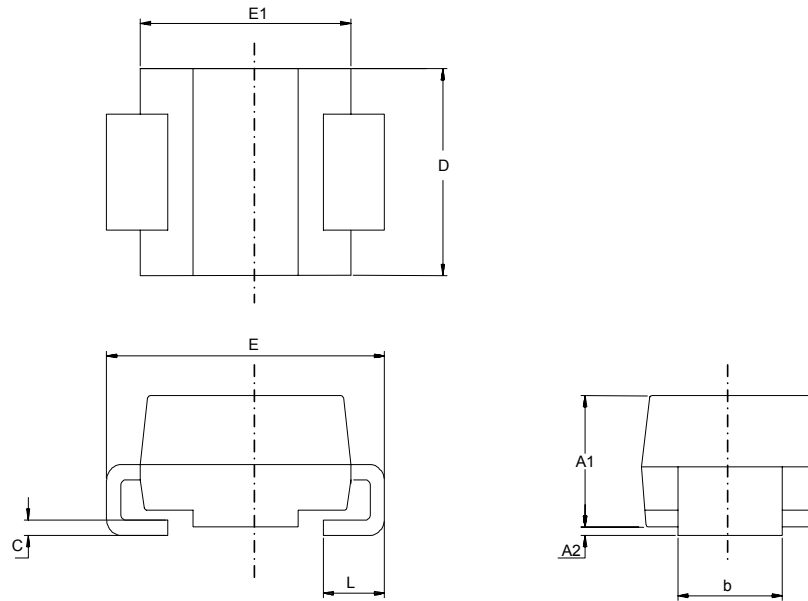
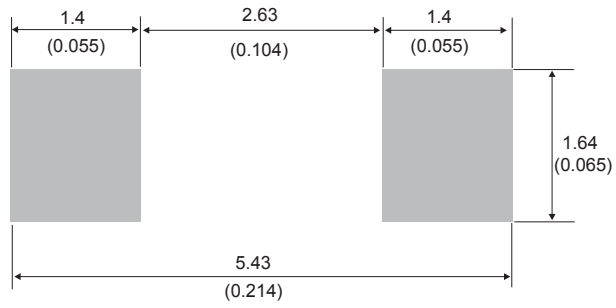


Table 6. SMA package mechanical data

Ref.	Dimensions			
	Millimeters		Inches (for reference only)	
	Min.	Max.	Min.	Max.
A1	1.90	2.45	0.074	0.097
A2	0.05	0.20	0.001	0.008
b	1.25	1.65	0.049	0.065
c	0.15	0.40	0.005	0.016
D	2.25	2.90	0.088	0.115
E	4.80	5.35	0.188	0.211
E1	3.95	4.60	0.155	0.182
L	0.75	1.50	0.029	0.060

Figure 9. SMA recommended footprint in mm (inches)





### 3 Ordering information

**Table 7. Ordering information**

Order code	Marking	Package	Weight	Base qty.	Delivery mode
STTH110	STTH110	DO-41	0.34 g	2000	Ammopack
STTH110A	H10	SMA	0.068 g	5000	Tape and reel 13"
STTH110RL	STTH110	DO-41	0.34 g	5000	Tape and reel 13"

## Revision history

**Table 8. Document revision history**

Date	Revision	Changes
Jan-2003	1	Initial release.
30-Sept-2009	2	Updated Table 8.
20-Dec-2013	3	Updated Table 4.
11-Dec-2019	4	Updated <a href="#">Table 3</a> .

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